

## PLATERONICS PROCESSING

### Minimum Plating Charges (effective 1/1/2021)

<u>Process</u>	<u>Specification</u>	<u>Minimum</u>
Bake (stress and embrittlement relief)	(over 12 -24hrs)	120.00
Bake (stress and embrittlement relief)	(over 4-12 hrs)	95.00
Bake (stress and embrittlement relief)	(under 4 hrs)	60.00
Bright Nickel	QQ-N-290	95.00
Bright Dip		65.00
Chemical Film (Yellow)	MIL-C-5541 CI 1A or 3	80.00
Chemical Film (Clear, RoHS compliant)	MIL-DTL-5541 Ty II	95.00
Clean, Etch, Strip, or Abrasive Blast		70.00
Copper	MIL-C-14550	95.00
Copper (Heavy Buildup)	AMS 2418 Ty II	130.00
Electroless Nickel	MIL-C-26074 CI 1	90.00
Electroless Nickel	CI 3,4	125.00
Electroless Nickel	CI 2	180.00
Gold	MIL-G(DTL)-45204 Ty II, II, II	250.00
Hard Anodize (non-dyed)	MII-A-8625 Ty III, CI 1	80.00
Hard Anodize (dyed)	MIL-A-8625 Ty III, CI 2	120.00
Hard Anodize (dyed or non-dyed with teflon coating)	MIL-A-8625 Ty III, CI 1	160.00
Mask		70.00
Passivation	QQ-P-35 or Equivalent	75.00
Silver	QQ-S-365 Ty 1,2	150.00
Stripping (most metals and substrates)		90.00
Sulfuric Anodize (non-dyed)	MII-A-8625 Ty II, CI 1	85.00
Sulfuric Anodize (dyed or dichromate seal)	MII-A-8625 Ty II, CI 2	95.00
Tin (Bright)	ASTM B545/MIL-T-10727 Ty I	100.00
Zinc (w/chromate or w/o chromate)	ASTM-B633 Ty I, II, III	95.00
Zinc (w/black chromate)	ASTM-B633 Ty II	110.00

If multiple processes are used, the minimum lot charges of each of the processes added together will apply. Minimum lot charge covers the first thirty minutes of work. Additional time will be billed using the hourly rates of processes involved. Information that is necessary in processing parts include: Applicable Specification(s), alloy and temper or Condition of material, thickness of plating required, close tolerances, critical areas to be free of rack marks, masking requirements. Please provide drawing whenever possible. Several items may be mixed to meet a single minimum lot charge by meeting the following criteria: The items must be of the same material and of similar configuration. They must be plated using the same process requirements and not require separate racking or tank runs.